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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10085869	02/28/2002	257	67	2811	P Cui
**APPLICANTS: Lo Wai Yew; Aripin Azhar Bin; Tiu Kong Bee;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO		
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no	SC11867MP		
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiner's initials					
TITLE : Stacked die semiconductor device					
U.S. DEPT. OF COMM./PAT. & TM-PTO-435L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL		Primary Examiner		
DISCLAIMER		PREPARED FOR ISSUE		
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